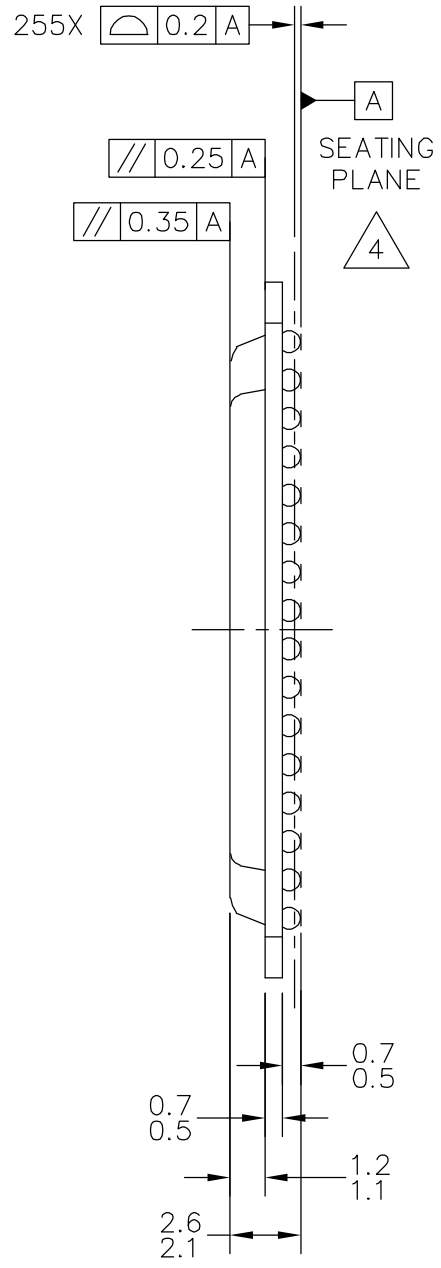
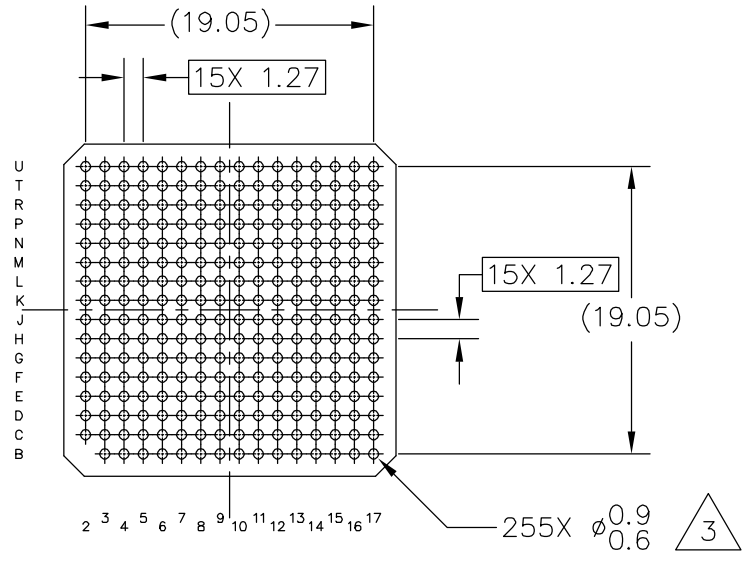


TOP VIEW



SIDE VIEW



BOTTOM VIEW

ϕ	$\phi 0.3$ (M)	A	B	C
	$\phi 0.15$ (M)	A		

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	STANDARD: JEDEC BAJ-1	
	SOT1711-1 06 MAR 2016	



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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